



# HD3SS6126 USB 3.0 和 USB 2.0 差分开关 2:1/1:2 多路复用/解复用器

## 1 特性

- 非常适合 USB 应用
  - 适用于 USB 3.0（超高速 USB 和 USB 2.0 HS/FS/LS）的信号开关
- 三个双向差分对通道多路复用/解复用开关还适用于 DisplayPort、PCIe Gen1/2/3、SATA 1.5/3/6G、AS 1.5/3/6G 和 XAUI 应用
- 高带宽路径 (SS) 最高支持 10Gbps 的数据速率
- $V_{CC}$  的工作范围为  $3.3V \pm 10\%$
- 高带宽路径 (SS) 上的 -3dB 差分带宽频率最高超过 10GHz
- 使用独特的适配方法在所支持的共模电压范围内保持恒定通道阻抗
- 出色的高带宽路径动态特性（2.5GHz 时）
  - 串扰 = -35dB
  - 隔音 = -23dB
  - 插入损耗 = -1.1dB
  - 回波损耗 = -11dB
- 3.5mm x 9mm、42 引脚小型晶圆级四方扁平无引线 (WQFN) 封装 (RUA)
- 激活模式功耗 = 8mW

## 2 应用

- 台式电脑
- 笔记本电脑
- 平板电脑
- 扩展坞
- 电信
- 电视

## 3 说明

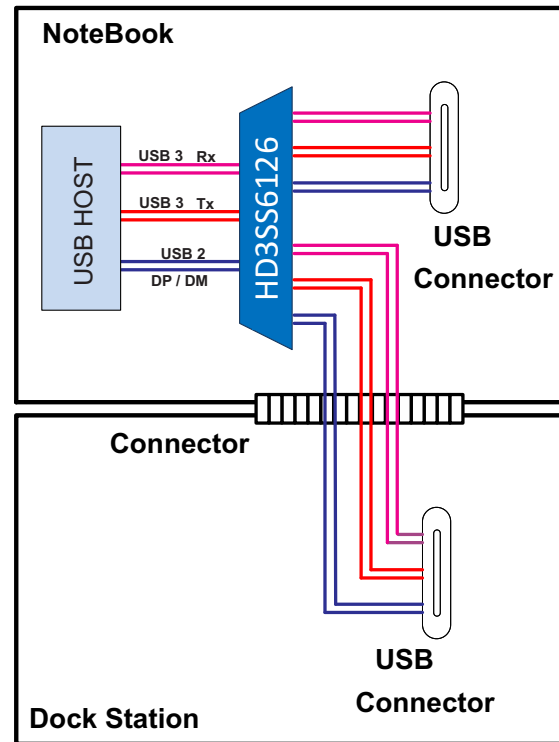
HD3SS6126 器件是一款针对 USB 应用而设计的高速无源开关，用于将 SuperSpeed USB RX 和 TX 以及 USB 2.0 DP 和 DM 信号从源位置路由到目标位置，反之亦然。该器件还可用于 DisplayPort、PCI Express、™SATA、SAS 和 XAUI 应用。HD3SS6126 器件可用于灌电流应用或拉电流应用。

器件信息<sup>(1)</sup>

器件型号	封装	封装尺寸（标称值）
HD3SS6126	WQFN (42)	9.00mm x 3.50mm

(1) 要了解所有可用封装，请见数据表末尾的可订购产品附录。

典型应用图



## 目录

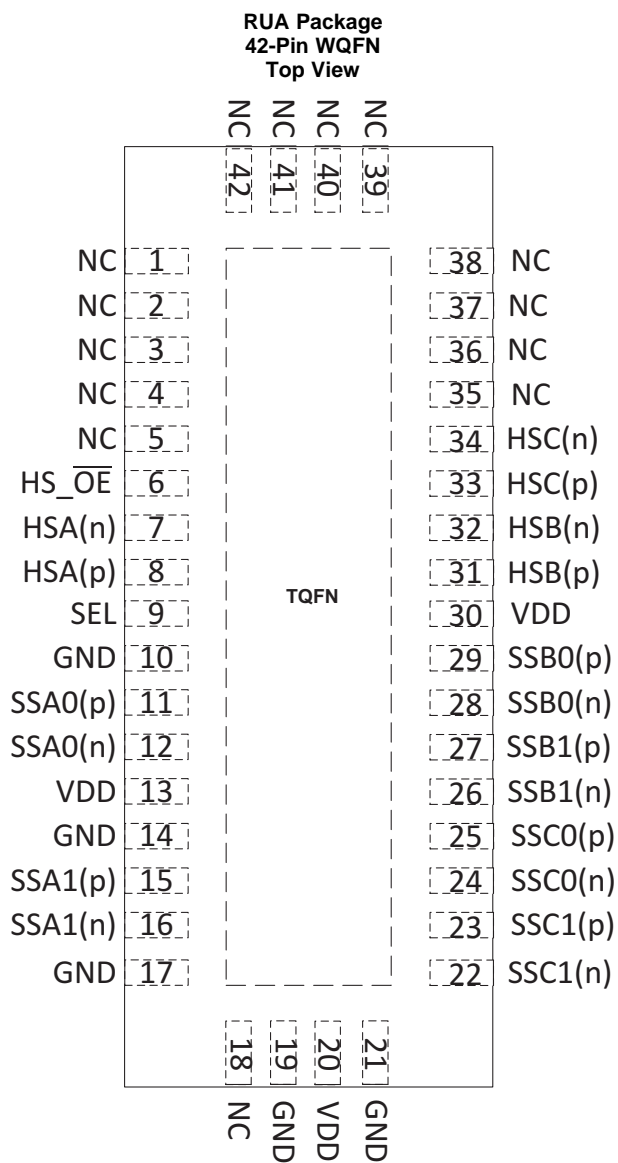
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## 4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Original (November 2013) to Revision A	Page
<ul style="list-style-type: none"> <li>已添加 引脚配置和功能部分，ESD 额定值表，典型特性部分，特性 描述 部分，器件功能模式，应用和实施部分，电源相关建议部分，布局部分，器件和文档支持部分以及机械、封装和可订购信息部分 .....</li> </ul>	1

## 5 Pin Configuration and Functions



**HD3SS6126**

ZHCSBS1A – NOVEMBER 2013 – REVISED AUGUST 2015

[www.ti.com.cn](http://www.ti.com.cn)
**Pin Functions**

PIN		I/O	DESCRIPTION
NAME	NO.		
GND	10, 14, 17, 19, 21	Supply	Ground
HSA(p)	8	I/O	Port A USB 2.0 positive signal
HSA(n)	7		Port A USB 2.0 negative signal
HSB(p)	31	I/O	Port B USB 2.0 positive signal
HSB(n)	32		Port B USB 2.0 negative signal
HSC(p)	33	I/O	Port C USB 2.0 positive signal
HSC(n)	34		Port C USB 2.0 negative signal
HS_ $\overline{\text{OE}}$	6	I (Control)	Output Enable H = Power Down L = Normal Operation
NC	1, 2, 3, 4, 5, 18, 35, 36, 37, 38, 39, 40, 41, 42	—	Electrically No Connection
SEL	9	I (Control)	USB 3.0/2.0 Port Selection Control Pins
SSA0(p)	11	I/O	Port A, Channel 0, USB 3.0 Positive Signal
SSA0(n)	12		Port A, Channel 0, USB 3.0 Negative Signal
SSA1(p)	15	I/O	Port A, Channel 1, USB 3.0 Positive Signal
SSA1(n)	16		Port A, Channel 1, USB 3.0 Negative Signal
SSB0(p)	29	I/O	Port B, Channel 0, USB 3.0 Positive Signal
SSB0(n)	28		Port B, Channel 0, USB 3.0 Negative Signal
SSB1(p)	27	I/O	Port B, Channel 1, USB 3.0 Positive Signal
SSB1(n)	26		Port B, Channel 1, USB 3.0 Negative Signal
SSC0(p)	25	I/O	Port C, Channel 0, USB 3.0 Positive Signal
SSC0(n)	24		Port C, Channel 0, USB 3.0 Negative Signal
SSC1(p)	23	I/O	Port C, Channel 1, USB 3.0 Positive Signal
SSC1(n)	22		Port C, Channel 1, USB 3.0 Negative Signal
VDD	13, 20, 30	Supply	3.3-V power supply voltage

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
Supply Voltage, $V_{DD}$ <sup>(2)</sup>		−0.3	4	V
Voltage	Differential I/O, High-bandwidth signal path: SSA0/1(p/n), SSB0/1(p/n), SSC0/1(p/n)	−0.5	4	V
	Differential I/O, Low-bandwidth signal path: HSAp(n), HSB(p/n), HSC(p/n)	−0.5	7	
	Control pin and single ended I/O	−0.3	$V_{DD} + 0.3$	
Continuous power dissipation		See <a href="#">Thermal Information</a>		
Storage temperature, $T_{stg}$		−65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to network ground terminal.

### 6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000	V
	Charged device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

typical values for all parameters are at  $V_{CC} = 3.3$  V and  $T_A = 25^{\circ}\text{C}$ ; all temperature limits are specified by design

			MIN	NOM	MAX	UNIT
$V_{DD}$	Supply voltage		3.0	3.3	3.6	V
$V_{IH}$	Input high voltage	Control Pins	2.0		$V_{DD}$	V
$V_{IL}$	Input low voltage	Control Pins	−0.1		0.8	V
$V_{IO\_Diff}$	Differential voltage	Switch I/O differential voltage for High-bandwidth signal path only: SSA0/1(p/n), SSB0/1(p/n), SSC0/1(p/n)	0		1.8	$V_{p-p}$
$V_{IO\_CM}$	Common voltage	Switch I/O common mode voltage for High-bandwidth signal path only: SSA0/1(p/n), SSB0/1(p/n), SSC0/1(p/n)	0		2.0	V
$T_A$	Operating free-air temperature		0		70	°C

## 6.4 Thermal Information

THERMAL METRIC		HD3SS6126	UNIT
		RUA (WQFN)	
		42 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	53.8	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	38.2	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	27.4	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter <sup>(1)</sup>	5.6	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter <sup>(1)</sup>	27.3	°C/W

(1) For more information about traditional and new thermal metrics, see *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#). Test conditions for  $\Psi_{JB}$  and  $\Psi_{JT}$  are clarified in the application report..

## 6.5 Electrical Characteristics – Device Parameters

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I <sub>CC</sub>	Supply current	V <sub>DD</sub> = 3.6 V, SEL = V <sub>DD</sub> /GND; $\overline{OE}$ = GND; Outputs Floating		2.4	3	mA
SEL						
I <sub>IH</sub>	Input high current	V <sub>DD</sub> = 3.6 V, V <sub>IN</sub> = V <sub>DD</sub>			95	μA
I <sub>IL</sub>	Input high current	V <sub>DD</sub> = 3.6 V, V <sub>IN</sub> = GND			1	μA
HS_ $\overline{OE}$						
I <sub>IH</sub>	Input high current	V <sub>DD</sub> = 3.6 V, V <sub>IN</sub> = V <sub>DD</sub>			1	μA
I <sub>IL</sub>	Input high current	V <sub>DD</sub> = 3.6 V, V <sub>IN</sub> = GND			1	μA
SSA0/1, SSB0/1, SSC0/1						
I <sub>LK</sub>	High-impedance leakage current	V <sub>DD</sub> = 3.6 V, V <sub>IN</sub> = 2 V, V <sub>OUT</sub> = 2 V, (I <sub>LK</sub> on open outputs Port B and C)			130	μA
		V <sub>DD</sub> = 3.6 V, V <sub>IN</sub> = 2 V, V <sub>OUT</sub> = 2 V, (I <sub>LK</sub> on open outputs Port A)			4	
HSA, HSB, HSC						
I <sub>LK</sub>	High-impedance leakage current	V <sub>DD</sub> = 3.6 V, V <sub>IN</sub> = 0 V, V <sub>OUT</sub> = 0 V to 4 V, HS_ $\overline{OE}$ _IN = GND			1	μA

## 6.6 Electrical Characteristics – Signal Switch Parameters

under recommended operating conditions;  $R_L$ ,  $R_{SC} = 50\ \Omega$ ,  $C_L = 10\ \text{pF}$  (unless otherwise noted)

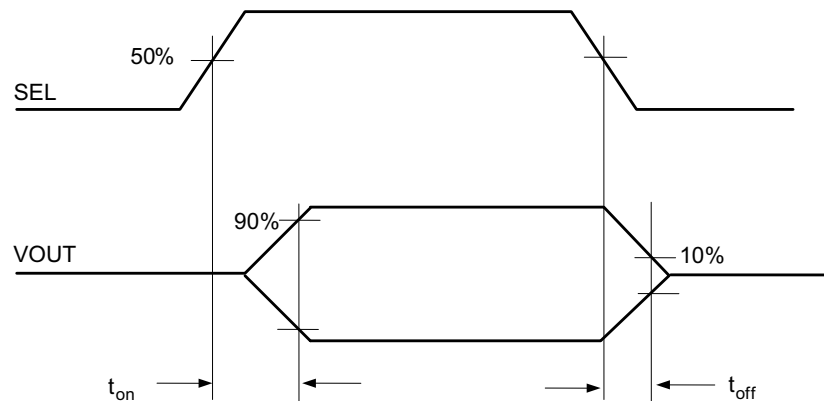
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>SSA0/1(p/n), SSB0/1(p/n), SSC0/1(p/n) Signal Path</b>						
$C_{ON}$	Outputs ON capacitance	$V_{IN} = 0\ \text{V}$ , outputs open, switch ON		1.5		pF
$C_{OFF}$	Outputs OFF capacitance	$V_{IN} = 0\ \text{V}$ , outputs open, switch OFF		1		pF
$R_{ON}$	Output ON resistance	$V_{DD} = 3.3\ \text{V}$ , $V_{CM} = 0\ \text{V} - 2\ \text{V}$ , $I_O = -8\ \text{mA}$		5	8	$\Omega$
$\Delta R_{ON}$	ON resistance match between pairs of the same channel	$V_{DD} = 3.3\ \text{V}$ ; $0\ \text{V} \leq V_{IN} \leq 2\ \text{V}$ ; $I_O = -8\ \text{mA}$			0.7	$\Omega$
$R_{FLAT\_ON}$	ON resistance flatness ( $R_{ON(MAX)} - R_{ON(MIN)}$ )	$V_{DD} = 3.3\ \text{V}$ ; $-0\ \text{V} \leq V_{IN} \leq 2\ \text{V}$			1.15	$\Omega$
$R_L$	Differential return loss ( $V_{CM} = 0\ \text{V}$ )	$f = 0.3\ \text{MHz}$		-25		dB
		$f = 2.5\ \text{GHz}$		-11		
		$f = 4\ \text{GHz}$		-11		
$X_{TALK}$	Differential crosstalk ( $V_{CM} = 0\ \text{V}$ )	$f = 0.3\ \text{MHz}$		-85		dB
		$f = 2.5\ \text{GHz}$		-35		
		$f = 4\ \text{GHz}$		-33		
$O_{IRR}$	Differential off-isolation ( $V_{CM} = 0\ \text{V}$ )	$f = 0.3\ \text{MHz}$		-85		dB
		$f = 2.5\ \text{GHz}$		-23		
		$f = 4\ \text{GHz}$		-21		
$I_L$	Differential insertion loss ( $V_{CM} = 0\ \text{V}$ )	$f = 0.3\ \text{MHz}$		-0.43		dB
		$f = 2.5\ \text{GHz}$		-1.1		
		$f = 4\ \text{GHz}$		-1.3		
BW	Bandwidth	At -3 dB		10		GHz
<b>HSA(p/n), HSB(p/n), HSC(p/n) SIGNAL PATH</b>						
$C_{ON}$	Outputs ON capacitance	$V_{IN} = 0\ \text{V}$ , Outputs Open, Switch ON		6	7.5	pF
$C_{OFF}$	Outputs OFF capacitance	$V_{IN} = 0\ \text{V}$ , Outputs Open, Switch OFF		3.5	6	pF
$R_{ON}$	Output ON resistance	$V_{DD} = 3\ \text{V}$ , $V_{IN} = 0\ \text{V}$ , $I_O = 30\ \text{mA}$		3	6	$\Omega$
		$V_{DD} = 3\ \text{V}$ , $V_{IN} = 2.4\ \text{V}$ , $I_O = 30\ \text{mA}$		3.4	6	
$\Delta R_{ON}$	ON resistance match between pairs of the same channel	$V_{DD} = 3\ \text{V}$ ; $V_{IN} = 0\ \text{V}$ ; $I_O = 30\ \text{mA}$		0.2		$\Omega$
		$V_{DD} = 3\ \text{V}$ ; $V_{IN} = 1.7\ \text{V}$ ; $I_O = -15\ \text{mA}$		0.2		
$R_{FLAT\_ON}$	ON resistance flatness ( $R_{ON(MAX)} - R_{ON(MIN)}$ )	$V_{DD} = 3\ \text{V}$ ; $V_{IN} = 0\ \text{V}$ ; $I_O = 30\ \text{mA}$		1		$\Omega$
		$V_{DD} = 3\ \text{V}$ ; $V_{IN} = 1.7\ \text{V}$ ; $I_O = -15\ \text{mA}$		1		
$X_{TALK}$	Differential crosstalk ( $V_{CM} = 0\ \text{V}$ )	$R_L = 50\ \Omega$ , $f = 250\ \text{MHz}$		-40		dB
$O_{IRR}$	Differential off-isolation ( $V_{CM} = 0\ \text{V}$ )	$R_L = 50\ \Omega$ , $f = 250\ \text{MHz}$		-41		dB
BW	Bandwidth	$R_L = 50\ \Omega$		0.9		GHz

## 6.7 Switching Characteristics

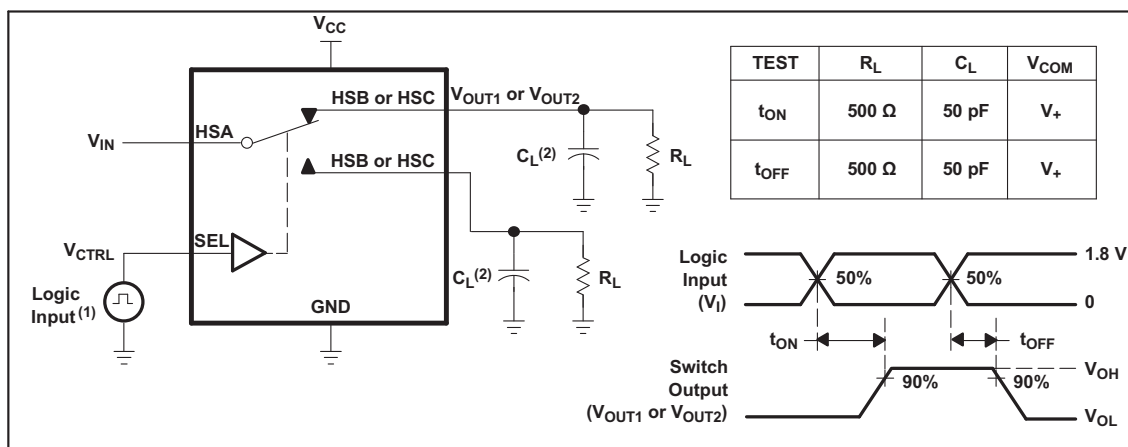
over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>SSA0/1(p/n), SSB0/1(p/n), SSC0/1(p/n) Signal Path</b>					
$t_{on}$	SEL-to-Switch $t_{on}$	$R_{SC}$ and $R_L = 50\ \Omega$ , See <a href="#">Figure 1</a>	70	250	ns
$t_{off}$	SEL-to-Switch $t_{off}$	$R_{SC}$ and $R_L = 50\ \Omega$ , See <a href="#">Figure 1</a>	70	250	ns
$t_{PD}$	Switch propagation delay	$R_{SC}$ and $R_L = 50\ \Omega$ , See <a href="#">Figure 3</a>		85	ps
$t_{SK(O)}$	Interpair output skew (CH-CH)	$R_{SC}$ and $R_L = 50\ \Omega$ , See <a href="#">Figure 3</a>		20	ps
$t_{SK(b-b)}$	Intrapair Output Skew (bit-bit)	$R_{SC}$ and $R_L = 50\ \Omega$ , See <a href="#">Figure 3</a>		8	ps
<b>HSA(p/n), HSB(p/n), HSC(p/n) SIGNAL PATH</b>					
$t_{ON}$	SEL to Switch $t_{ON}$	See <a href="#">Figure 2</a>		30	ns
	HS $\overline{OE}$ to Switch $t_{ON}$	See <a href="#">Figure 2</a>		17	
$t_{OFF}$	SEL to Switch $t_{OFF}$	See <a href="#">Figure 2</a>		12	ns
	HS $\overline{OE}$ to Switch $t_{OFF}$	See <a href="#">Figure 2</a>		10	
$t_{PD}^{(1)}$	Switch propagation delay	See <a href="#">Figure 3</a>	250		ps
$t_{SK(O)}^{(1)}$	Interpair output skew (CH-CH)		100	200	ps
$t_{SK(P)}^{(1)}$	Intrapair Output Skew (bit-bit)		100	200	ps

(1) Specified by design



**Figure 1. Select to Switch  $t_{ON}$  and  $t_{OFF}$**

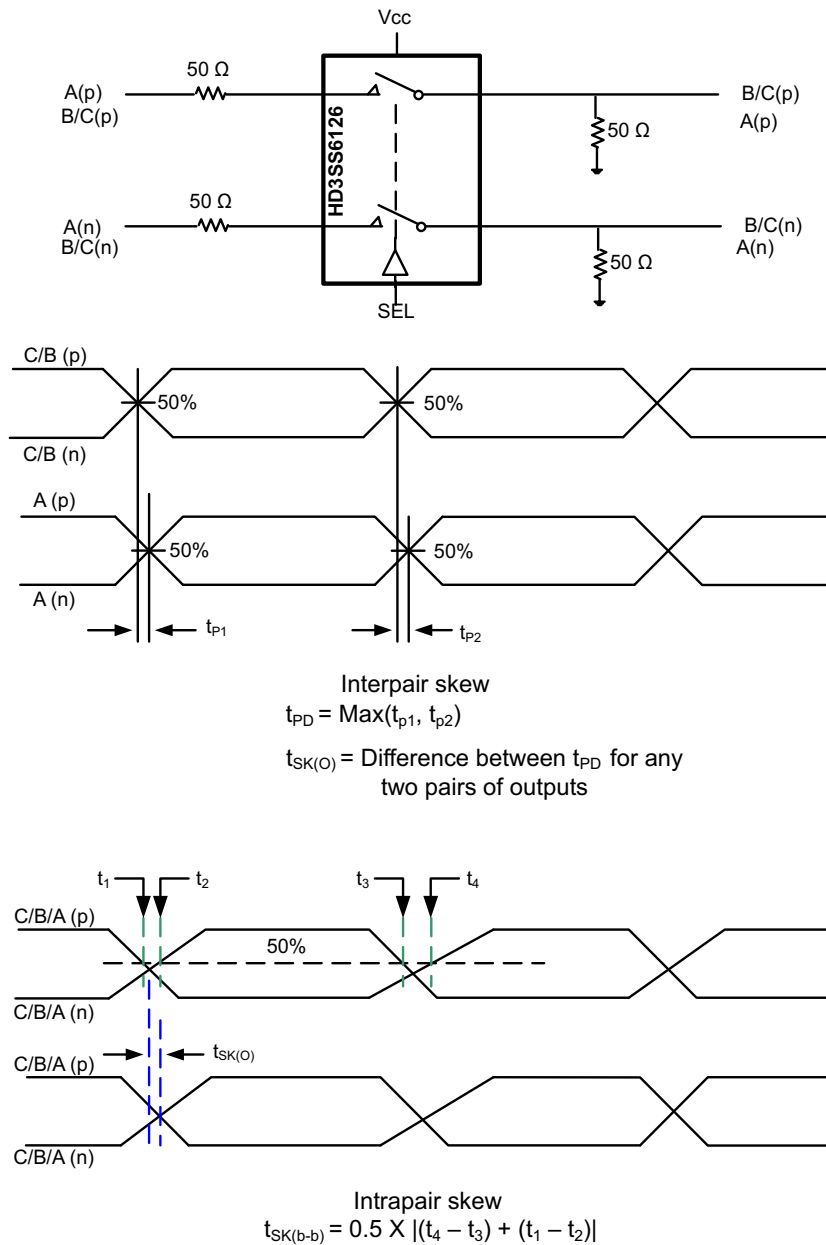


(1) All input pulses are supplied by generators have the following characteristics: PRR  $\leq 10$  MHz,  $Z_O = 50\ \Omega$ ,  $t_r < 5$  ns,  $t_f < 5$  ns.

(2)  $C_L$  includes probe and jig capacitance.

**Figure 2. Turnon ( $t_{ON}$ ) and Turnoff Time ( $t_{OFF}$ )**



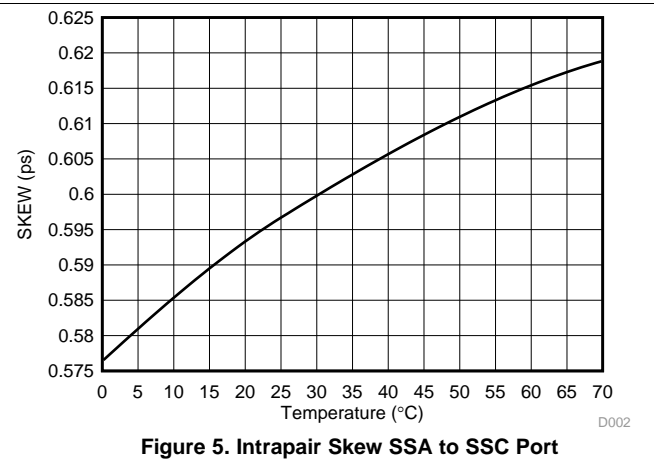
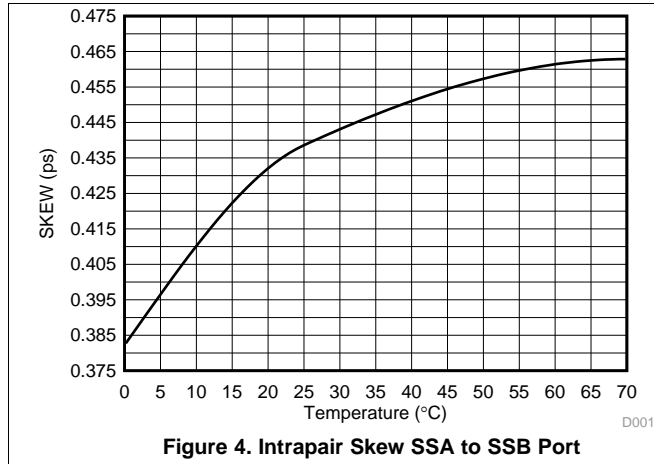


**NOTES:**

1. Measurements based on an ideal input with zero intrapair skew on the input, i.e. the input at A to B/C or the input at B/C to A
2. Interpair skew is measured from lane to lane on the same channel, e.g. C0 to C1
3. Intrapair skew is defined as the relative difference from the p and n signals of a single lane

**Figure 3. Propagation Delay and Skew**

## 6.8 Typical Characteristics

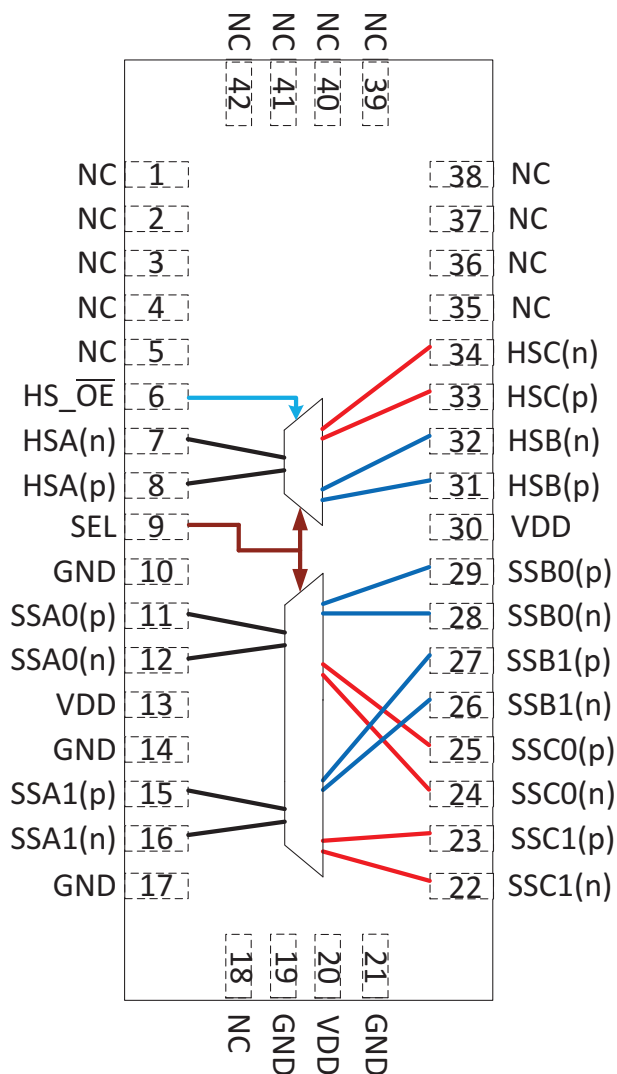


## 7 Detailed Description

### 7.1 Overview

The HD3SS6126 is a USB 3.0 and USB 2.0 differential switch, it is designed to support data rates up to 10 Gbps on high-bandwidth paths (SS), it is also suitable for DisplayPort, PCIe Gen1/2/3, SATA 1.5/3/6G, SAS 1.5/3/6G and XAUI applications. The device uses a unique adaptation method to maintain a constant channel impedance over the supported common-mode voltage range, resulting in an excellent high-bandwidth path dynamic characteristics (at 2.5 GHz; Crosstalk = -35 dB, Isolation = -23 dB, Insertion Loss = -1.1 dB, Return Loss = -11 dB).

## 7.2 Functional Block Diagram



## 7.3 Feature Description

The HD3SS6126 can be powered by VBUS from the USB Host, and is capable of selecting USB2 independently from USB3. Although the main application of the HD3SS6126 is USB3.0/2.0, the device also supports common interfaces such as PCIe Gen1 and Gen2, DP and SATA/SAS applications. The device is able to support these additional interfaces because of its support of data rates up to 5.4 Gbps and common-mode voltages from 0 V to 2 V with a maximum signal swing of 1.8 V. All of these applications use an 8b or 10b coding technique to achieve DC balance and facilitate terminal equipment.

### NOTE

The device may need AC capacitors and additional bias voltage to support the PCIe Gen1 and Gen2 interfaces.

## 7.4 Device Functional Modes

**Table 1. Truth Table USB 3.0 SuperSpeed USB**

SEL	USB 3.0 PORT SELECTION		
	SSA0/1	SSB0/1	SSC0/1
0	To/From SSB0/1	To/From SSA0/1	Off
1	To/From SSC0/1	Off	To/From SSA0/1

**Table 2. Truth Table USB 2.0 High-Speed, Full-Speed, Low-Speed Path**

HS_ÖE	SEL	USB 2.0 Port Selection		
		HSA	HSB	HSC
0	0	To/From HSB	To/From HSA	Off
0	1	To/From HSC	Off	To/From HSA
1	X	Off	Off	Off

## 8 Application and Implementation

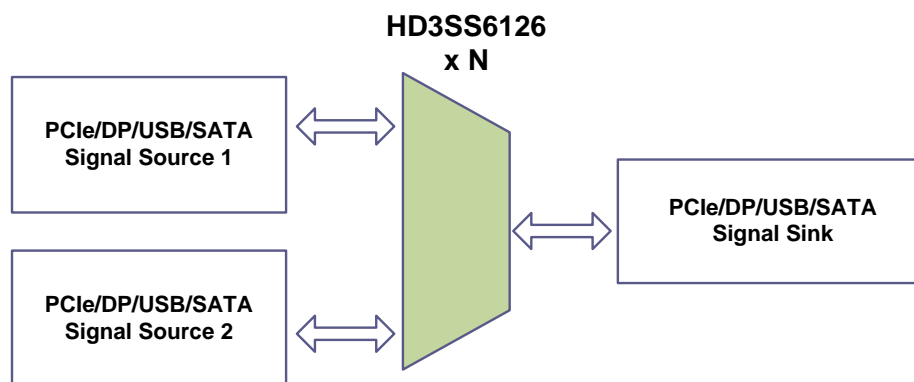
### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

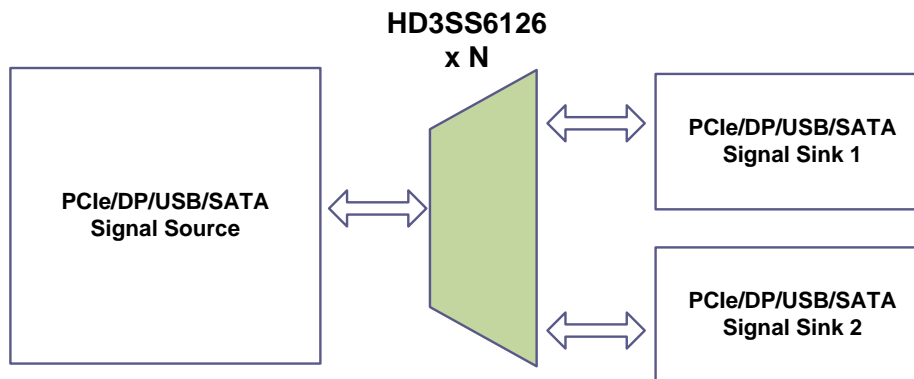
### 8.1 Application Information

A typical application for the HD3SS6126 is a USB 3.0 KVM switch, where one of two USB hosts system can be selected for an USB device. These guidelines are also suitable for PCIe(Gen1,Gen2), SATA, XAUI and DP, since the HD3SS6126 device is fully compatible with these protocols.

### 8.2 Typical Application



**Figure 6. Two Signal Sources to One Destination**



**Figure 7. One Signal Sources to Two Destination**

## Typical Application (continued)

### 8.2.1 Design Requirements

Power supply requirements:

- $V_{DD}$  from 3 V to 3.6 V

Control pins requirements

- $V_{IH}$  from 2 V to  $V_{DD}$
- $V_{IL}$  from -0.1 V to 0.8 V

Differential pairs requirements:

- $V_{I/O\_Diff}$  from 0 V to 1.8 Vp-p
- $V_{I/O\_CM}$  from 0 V to 2 V

$T_A$  Operating free-air temperature from 0°C to 70°C

### 8.2.2 Detailed Design Procedure

#### 8.2.2.1 Power Supply

The first step is to design the power supply and determine the  $V_{CC}$  stability and minimum current required (see [Power Supply Recommendations](#)).

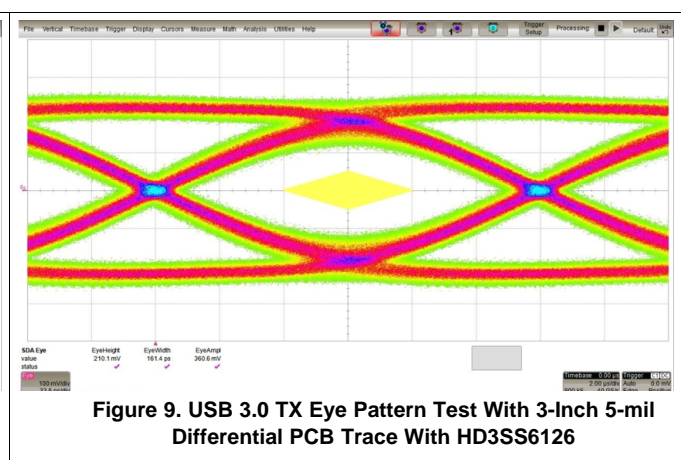
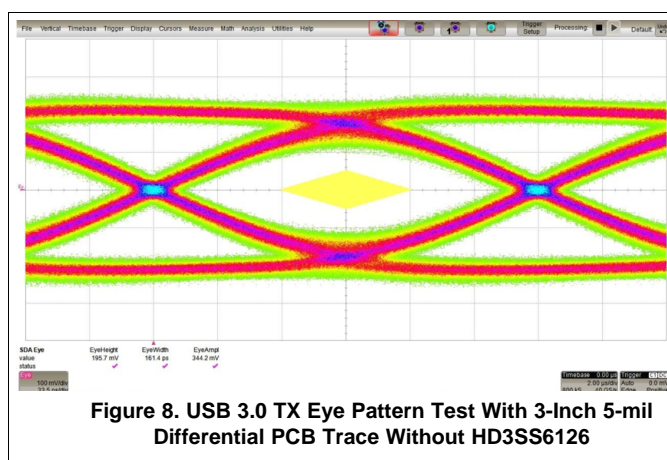
#### 8.2.2.2 Differential Pairs

All of the interfaces the HD3SS6126 device supports require AC coupling between the transmitter and receiver. TI recommends using 0402-sized capacitors to provide AC coupling, but 0603-sized capacitors are also acceptable. Both 0805-sized capacitors and C-packs should be avoided. Best practice is to place AC-coupling capacitors symmetrically. A capacitor value of 0.1 $\mu$ F is best and the value should be matched for the +/-signal pair. The placement should be along the TX pairs on the system board, which are usually routed on the top layer of the board.

All differential pairs must have a matched impedance according to the implemented protocol: 100- $\Omega$  differential ( $\pm 15\%$ ) for PCIe and 90- $\Omega$  differential ( $\pm 15\%$ ) for USB 2.0 and USB 3.0.

The control logic can be implemented by use of an external control processor or by using a simple selector switch. TI recommends using 5-k $\Omega$  pullup and pulldown resistors on the control signals, if they are included. The control logic must not violate the input voltage parameters outlined in the [Recommended Operating Conditions](#) table.

### 8.2.3 Application Curves



## 9 Power Supply Recommendations

The power supply must provide a constant voltage with a 10% maximum variation of the nominal value, and has to be able to provide at least 3 mA for the HD3SS6126 only (based on the maximum power consumption). It is also possible to provide the power supply from VBUS from the Host, just by including a voltage regulator powered through VBUS. Each  $V_{CC}$  pin must have a 0.1- $\mu$ F bypass capacitor placed as closely as possible. TI recommends including two extra capacitors in parallel, which should be also placed as closely as possible to the  $V_{CC}$  pin. The suggested values for these extra capacitors are 1  $\mu$ F and 0.01  $\mu$ F.

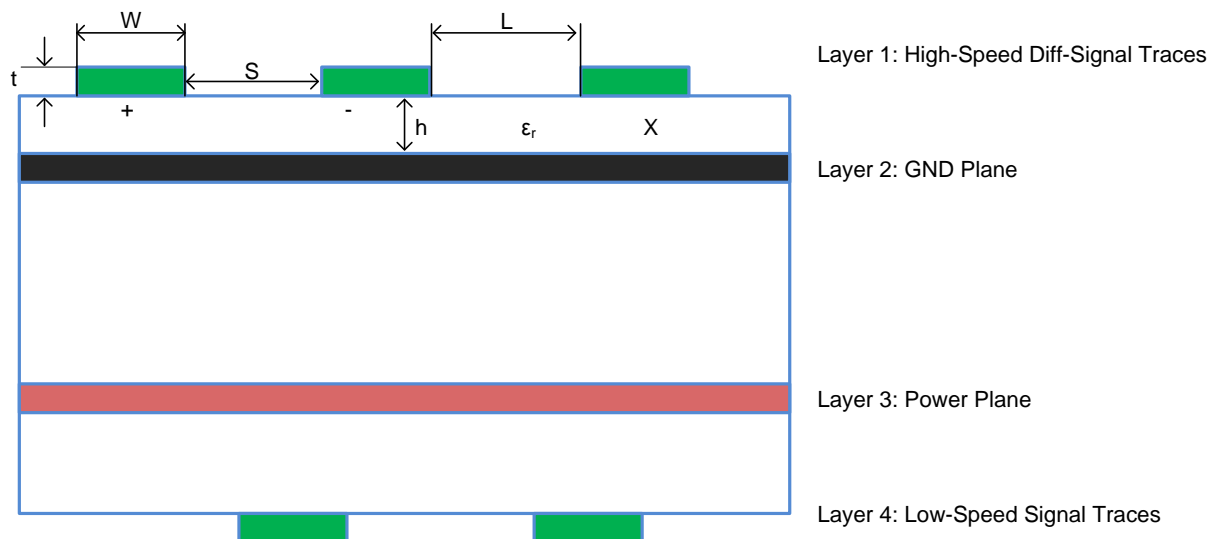
## 10 Layout

### 10.1 Layout Guidelines

Generally, impedance match becomes critical in such high-speed signal applications to avoid reflection. Each differential-signal pair must have a differential impedance of about  $90\ \Omega \pm 15\%$  (for PCIe or DP,  $100\ \Omega \pm 10\%$ ) with single-end signal impedance about  $50\ \Omega$  to ground. Usually, Microstrip is used to accomplish impedance match. Four layers are recommended for a low-EMI PCB design. shows physical geometries of differential traces to form Microstrip. In order to better maintain signal integrity, reference the following:

1. Route high-speed differential signals on the top layer with a solid ground layer under them to accomplish controlled impedance, while avoiding vias and stubs which may cause impedance discontinuities. If vias must be used, make sure the space of the vias is as minimal as possible.
2. Be sure both the length of differential traces and the length of differential signal pairs are matched in order to reduce intrapair skew and interpair skew separately which also does good to low EMI. TI recommends keeping the space of the traces of the differential signal the same across the entire length of the trace to keep impedance match and reduce EMI.
3. Route low-speed, but fast-edged control signals on the bottom layer to minimize the crosstalk of the high-speed signal.
4. For other adjacent signal traces on the same layer, make distance  $L \geq 3S$  to facilitate impedance match.
5. TI recommends using  $45^\circ$  bends instead of  $90^\circ$  bends in order to maintain signal integrity and low EMI.

### 10.2 Layout Examples



**Figure 10. PCB Layers Example**

## Layout Examples (continued)

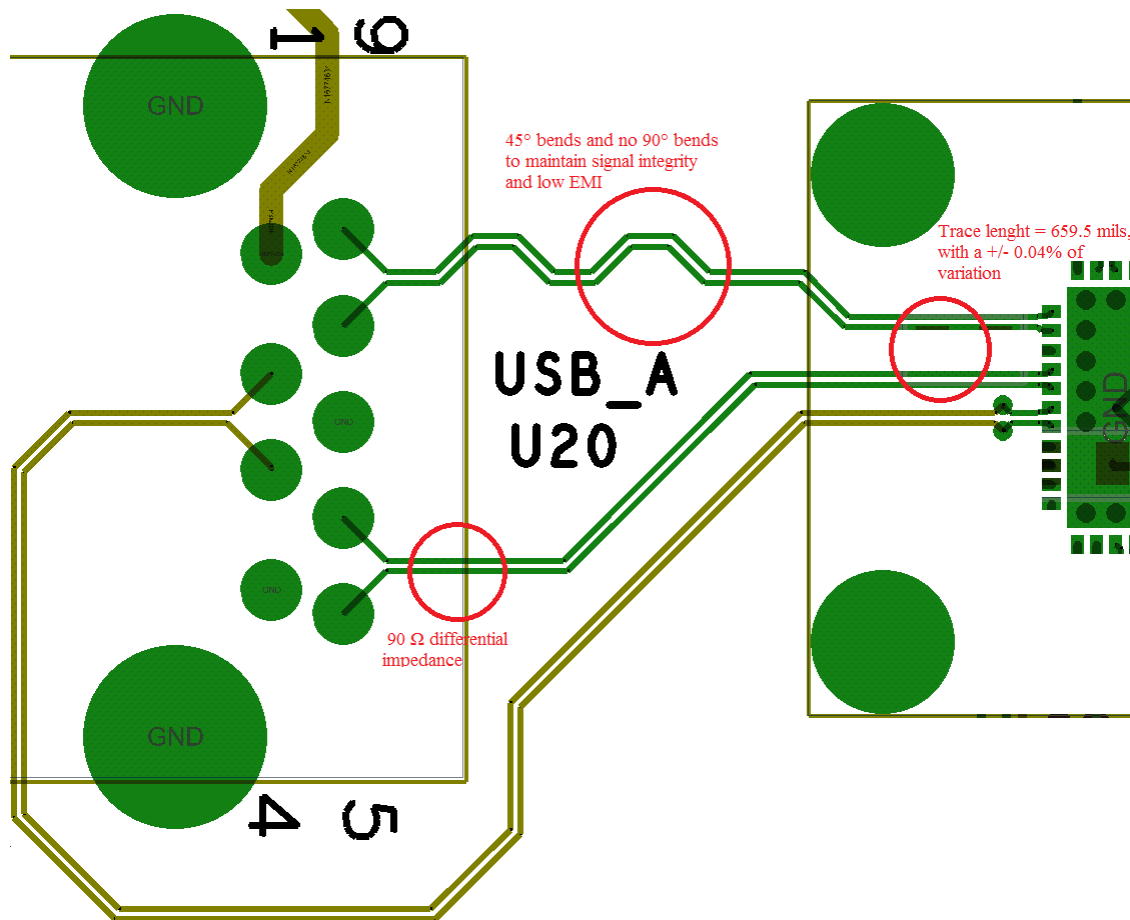


Figure 11. USB Signals Routing Example



## 11 器件和文档支持

### 11.1 社区资源

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### 11.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。这些信息是针对指定器件可提供的最新数据。这些数据会在无通知且不对本文档进行修订的情况下发生改变。欲获得该数据表的浏览器版本，请查阅左侧的导航栏。

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数据转换器	<a href="http://www.ti.com.cn/dataconverters">www.ti.com.cn/dataconverters</a>	消费电子	<a href="http://www.ti.com.cn/consumer-apps">www.ti.com.cn/consumer-apps</a>
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DSP - 数字信号处理器	<a href="http://www.ti.com.cn/dsp">www.ti.com.cn/dsp</a>	工业应用	<a href="http://www.ti.com.cn/industrial">www.ti.com.cn/industrial</a>
时钟和计时器	<a href="http://www.ti.com.cn/clockandtimers">www.ti.com.cn/clockandtimers</a>	医疗电子	<a href="http://www.ti.com.cn/medical">www.ti.com.cn/medical</a>
接口	<a href="http://www.ti.com.cn/interface">www.ti.com.cn/interface</a>	安防应用	<a href="http://www.ti.com.cn/security">www.ti.com.cn/security</a>
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无线连通性	<a href="http://www.ti.com.cn/wirelessconnectivity">www.ti.com.cn/wirelessconnectivity</a>	德州仪器在线技术支持社区	<a href="http://www.deyisupport.com">www.deyisupport.com</a>

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## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
HD3SS6126RUAR	ACTIVE	WQFN	RUA	42	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	0 to 70	HD3SS6126	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
HD3SS6126RUAR	WQFN	RUA	42	3000	330.0	16.4	3.8	9.3	1.0	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS

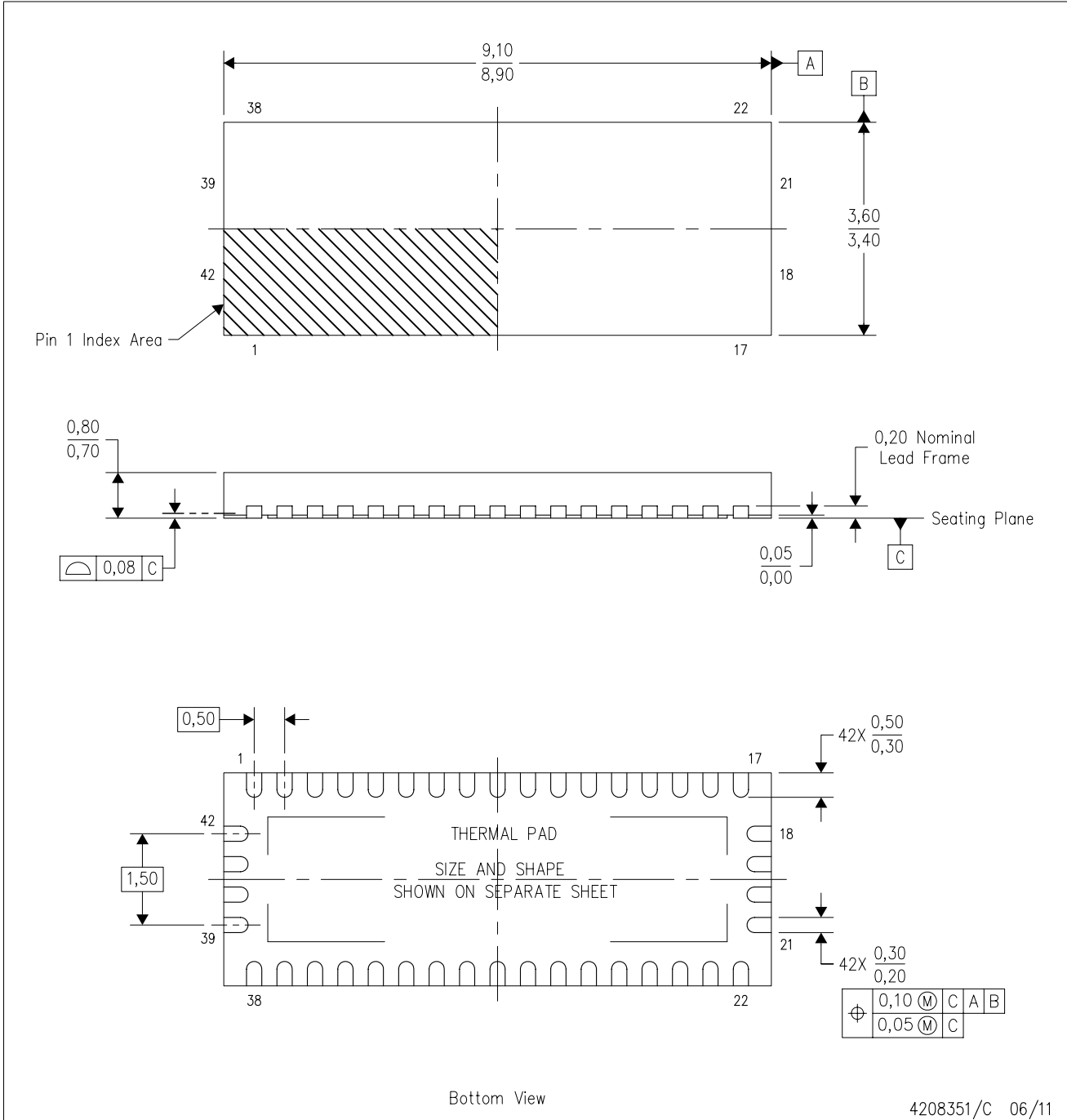


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
HD3SS6126RUAR	WQFN	RUA	42	3000	367.0	367.0	38.0

RUA (R-PWQFN-N42)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - QFN (Quad Flatpack No-Lead) package configuration.
  - The package thermal pad must be soldered to the board for thermal and mechanical performance.
  - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.

## THERMAL PAD MECHANICAL DATA

RUA (R-PWQFN-N42)

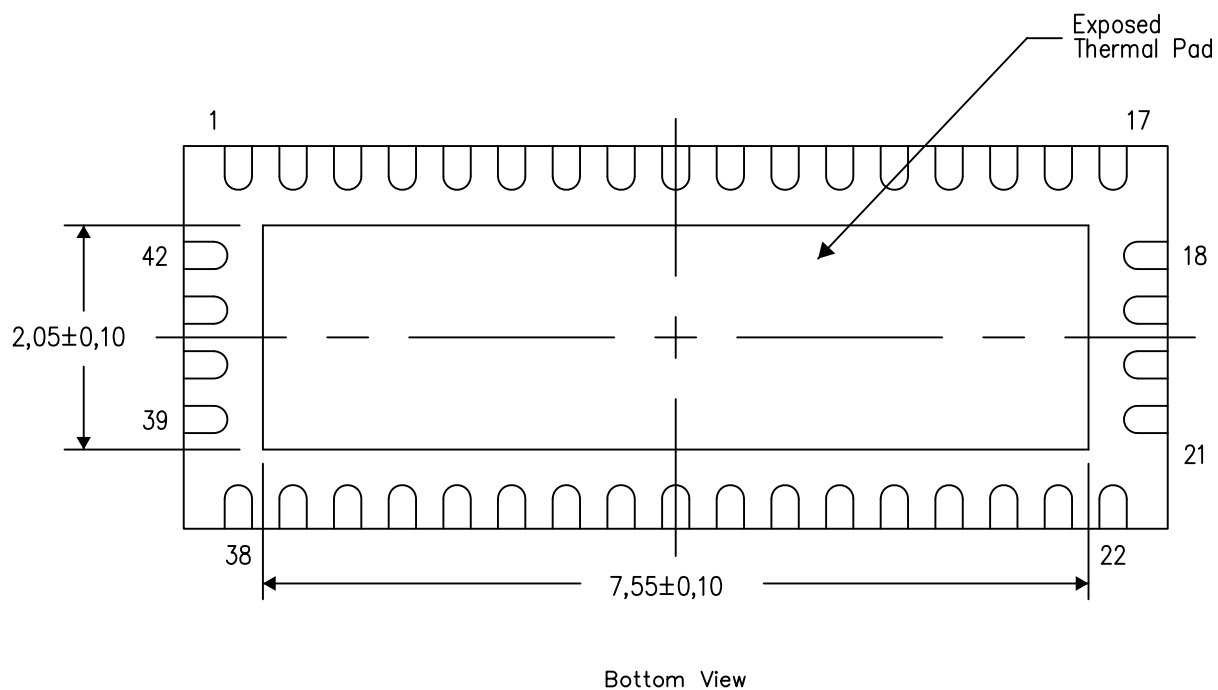
PLASTIC QUAD FLATPACK NO-LEAD

### THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Exposed Thermal Pad Dimensions

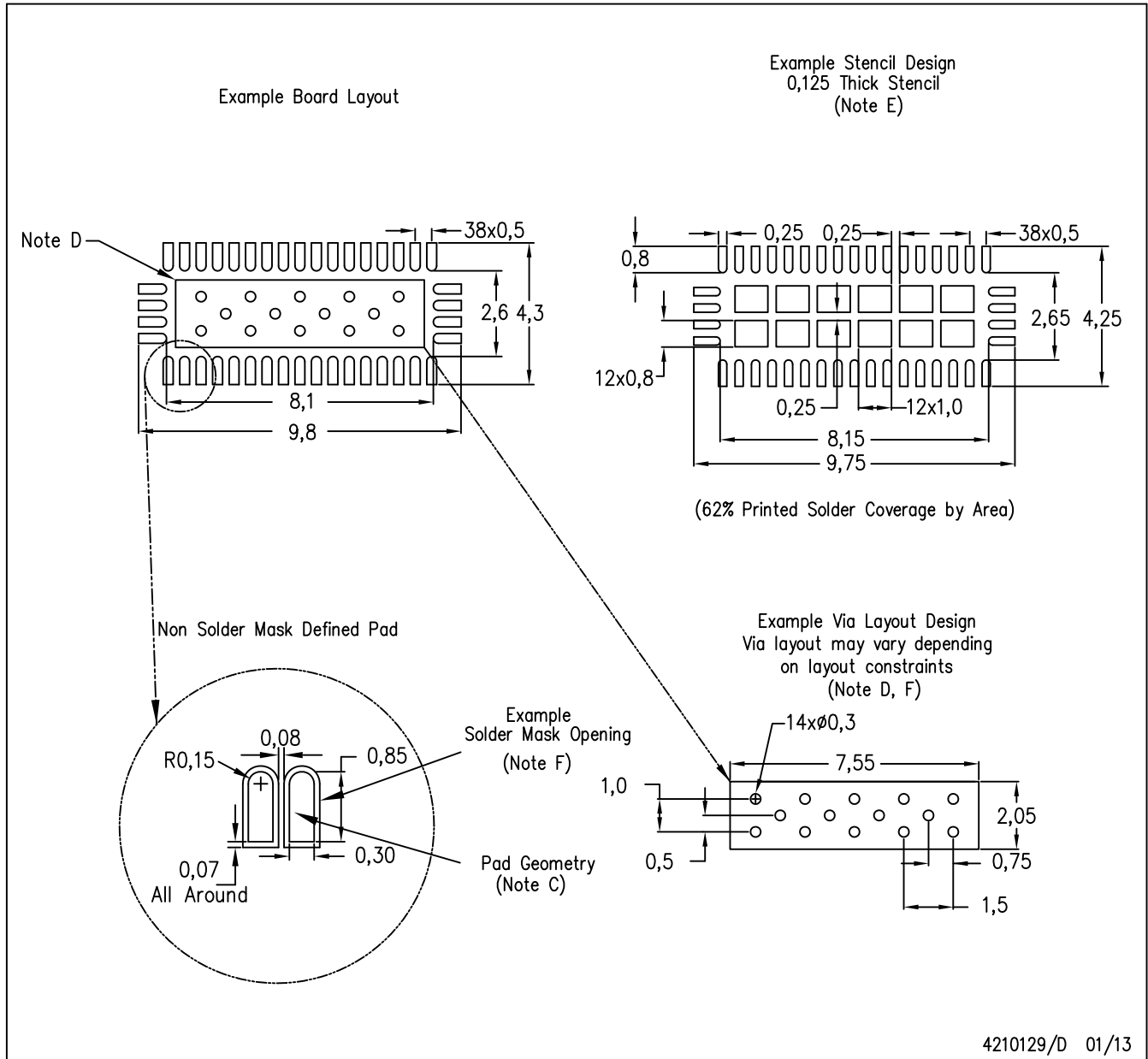
4208352/E 01/13

NOTE: All linear dimensions are in millimeters



RUA (R-PWQFN-N42)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
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放大器和线性器件	<a href="http://www.ti.com.cn/amplifiers">www.ti.com.cn/amplifiers</a>	计算机及周边	<a href="http://www.ti.com.cn/computer">www.ti.com.cn/computer</a>
数据转换器	<a href="http://www.ti.com.cn/dataconverters">www.ti.com.cn/dataconverters</a>	消费电子	<a href="http://www.ti.com.cn/consumer-apps">www.ti.com.cn/consumer-apps</a>
DLP® 产品	<a href="http://www.dlp.com">www.dlp.com</a>	能源	<a href="http://www.ti.com.cn/energy">www.ti.com.cn/energy</a>
DSP - 数字信号处理器	<a href="http://www.ti.com.cn/dsp">www.ti.com.cn/dsp</a>	工业应用	<a href="http://www.ti.com.cn/industrial">www.ti.com.cn/industrial</a>
时钟和计时器	<a href="http://www.ti.com.cn/clockandtimers">www.ti.com.cn/clockandtimers</a>	医疗电子	<a href="http://www.ti.com.cn/medical">www.ti.com.cn/medical</a>
接口	<a href="http://www.ti.com.cn/interface">www.ti.com.cn/interface</a>	安防应用	<a href="http://www.ti.com.cn/security">www.ti.com.cn/security</a>
逻辑	<a href="http://www.ti.com.cn/logic">www.ti.com.cn/logic</a>	汽车电子	<a href="http://www.ti.com.cn/automotive">www.ti.com.cn/automotive</a>
电源管理	<a href="http://www.ti.com.cn/power">www.ti.com.cn/power</a>	视频和影像	<a href="http://www.ti.com.cn/video">www.ti.com.cn/video</a>
微控制器 (MCU)	<a href="http://www.ti.com.cn/microcontrollers">www.ti.com.cn/microcontrollers</a>		
RFID 系统	<a href="http://www.ti.com.cn/rfidsys">www.ti.com.cn/rfidsys</a>		
OMAP应用处理器	<a href="http://www.ti.com.cn/omap">www.ti.com.cn/omap</a>		
无线连通性	<a href="http://www.ti.com.cn/wirelessconnectivity">www.ti.com.cn/wirelessconnectivity</a>	德州仪器在线技术支持社区	<a href="http://www.deyisupport.com">www.deyisupport.com</a>

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